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PATENT
YOR920030206US1

IN THE UNITED STATES PATENT & TRADEMARK OFFICE

In re Application of	:	Larry Shungwei Mok
Serial Number	:	10/784,624
Filing Date	:	02/23/2004
Examiner	:	Tho V. Duong
Group Art Unit	:	3753
For	:	HEAT DISSIPATION INTERFACE FOR SEMICONDUCTOR CHIP STRUCTURES

Sir:

In response to the Official Action dated June 27, 2008, please amend the above-identified application as follows:

In the Specification:

The Examiner has objected to the inclusion of "micrometer" in Claim 3. The specification recites that the thickness of the side should be expressed in "millimeters." Claim 3 has been amended to recite that the thickness is expressed in "millimeters."

In the Drawings:

Applicants have cancelled the language in Claim 1 that referred to the contact between fin and side wall of the beam. Thus no amended drawing is required.

In the Claims:

Please cancel Claim 5 and amend the other pending Claims as set forth in the Appendix attached hereto.